

Amendments To The Claims

Claims 1-22 (Canceled)

Claim 23 (new): A surface mountable light emitting device, comprising:

- a first light emitting semiconductor chip secured with a body;
- a first thermally and electrically conductive lead frame connected to said first chip and exposed over a portion of an underside of the body;
- a first lead wire from said first chip to a first contact exposed at least partially on a side of the body; and
- a first lens substantially encasing an upper surface of said first chip, where the first lens forms part of the body about the first lead frame and redistributes radiant emissions from the first chip externally into a substantial solid angle.

Claim 24 (new): The device of claim 23, wherein the first lens comprises a generally transparent compound that is keyed into the first conductive lead frame and said first contact.

Claim 25 (new): The device of claim 23, further comprising:

- a reflector cup about said first chip that reflects light from sides of the first chip generally into a direction extending from the upper surface of said first chip.

Claim 26 (new): The device of claim 25, wherein said reflector cup comprises a core material with a highly reflective metallic coating.

Claim 27 (new): The device of claim 23, wherein the first lens comprises a lower transfer section operable for placement upon the first light emitting semiconductor chip.

Claim 28 (new): The device of claim 27, wherein the first lens comprises an upper ejector section situated upon the lower transfer section such that the radiant emissions are transferred through the lower transfer section to the upper ejector section where the radiant emissions are redistributed externally from the upper ejector section into the substantial solid angle.

Claim 29 (new): The device of claim 23, wherein the first lens further comprises an upper ejector section situated such that the radiant emissions are transferred from the first chip to the upper ejector section such that the radiant emissions are redistributed externally from the upper ejector section into the substantial solid angle.

Claim 30 (new): The device of claim 29, wherein the first upper ejector section is a cylinder having a conical depression on its top surface.

Claim 31 (new): The device of claim 23, further comprising:
a second light emitting semiconductor chip;
a second thermally and electrically conductive lead frame connected to said second chip and exposed on the underside of the body;
a second lead wire from said second chip to a second contact exposed at least partially on the side of said body; and
a second lens substantially encasing an upper surface of said second chip.

Claim 32 (new): The device of claim 31, wherein the first lens substantially encases the upper surface of the first chip, and the second lens substantially encases the upper surface of the second chip.

Claim 33 (new): The device of claim 31, wherein the first and second lenses extend to form part of the body about the first and second conductive lead frames.

Claim 34 (new): The device of claim 23, wherein the first lens substantially encases the upper surface of the first chip, and the first lens extends to form part of the body about the first and second conductive lead frames.

Claim 35 (new): A surface mountable light emitting device, comprising:
a light emitting semiconductor chip incorporated into a body;
a conductive lead frame connected to said chip and exposed on an underside of the body;
and
a lens over said chip and positioned on an opposite side of the body as the underside of the body, wherein the lens comprises:
a lower transfer section; and
an upper ejector section situated upon the lower transfer section, said lower transfer section operable for placement upon the light emitting semiconductor chip and operable to transfer the radiant emission to said upper ejector section, said upper ejector section shaped such that the emission is redistributed externally into a substantial solid angle.

Claim 36 (new): The device of claim 34, wherein the conductive lead is a thermally conductive lead.

Claim 37 (new): The device of claim 36, wherein the lens substantially encases an upper surface of said chip, where the lens forms part of the body.

Claim 38 (new): The device of claim 37, wherein the upper ejector section is a cylinder having a conical depression on its top surface.